

Serial No. 09/821,722

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Art Unit: 2827

2. The interconnection device of claim 1 wherein said conductive inner layer trace extends outward from the edge of the interconnection device.

REMARKS

Claims 1 – 6, 12, and 13 are pending in the Application. Reconsideration and further examination is respectfully requested.

Claim Rejections – 35 USC §112

Claims 1 – 6, 12, and 13 were rejected under 35 USC 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter of the invention, because the phrase “printed wiring board” lacks antecedent basis. In accordance with the Examiner’s suggestions, Claims 1 and 2 have been amended to recite the “interconnection device” recited in the preamble of Claim 1. The Applicant therefore respectfully requests that this rejection be withdrawn.

Claim Rejections – 35 USC § 102

1. Claims 1 – 6 and 12 were rejected under 35 USC 102(b) as being anticipated by U.S. Patent No. 5,136,471 to Inasaka (“Inasaka”). This rejection is respectfully traversed.

The Applicant’s independent claim 1 recites:

“An interconnection device comprising: